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** CONTINUING DATA *****

none JJ

** FOREIGN APPLICATIONS *****

JAPAN 2002-322678 11/06/2002

JAPAN 2002-340384 11/25/2002

JAPAN 2002-342329 11/26/2002

OK JJ

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance		DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged <i>[Signature]</i>	 <i>[Signature]</i>	JAPAN	13	54	9

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TITLE

Solder alloy material layer composition, electroconductive and adhesive composition, flux material layer composition, solder ball transferring sheet, bump and bump forming process, and semiconductor device

 All Fees 1.16 Fees (Filing)

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